



**WANSEMI**  
万芯半导体

**WP8804K**

# Enhancement Mode N-Channel Power MOSFET

TSSOP8/NMOS/20V/ $\pm 12$ V/0.8V/5.5A/20m $\Omega$

Rev0.5

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## 20V, 20mΩ, 5.5A, N-Channel MOSFET

### 1.Features

- ◆ High Power and current handling capability
- ◆ Lead free product is acquired
- ◆ Surface Mount Package

V <sub>DS</sub> Typ.	R <sub>DS(on)</sub> Typ.	I <sub>D</sub> Max.
20V	20mΩ @ 4.5V	5.5A
	27mΩ @ 2.5V	

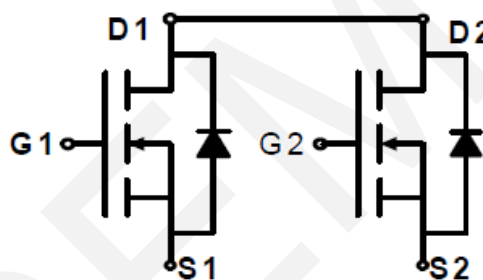
### 2.Applications

- ◆ Battery Protection
- ◆ Battery Powered Systems
- ◆ Power Management in Notebook Computer
- ◆ Portable Equipment



TSSOP8

Pin Description



Schematic Diagram

### 3.Package Marking and Ordering Information

Part no.	Marking	Package	PCS/Reel	PCS/CTN.
WP8804K	8804	TSSOP8	5,000	80,000

### 4.Absolute Max Ratings at Ta=25°C (Note1)

Parameter	Symbol	Maximum	Units
Drain to Source Voltage	V <sub>DSS</sub>	20	V
Gate to Source Voltage	V <sub>GSS</sub>	±12	V
Drain Current-Continuous	I <sub>D</sub>	5.5	A
Drain Current (Pulse)	I <sub>DM</sub>	22	A
Maximum Power Dissipation	P <sub>D</sub>	1.9	W
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	-55 to +150	°C
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)	T <sub>L</sub>	260	°C

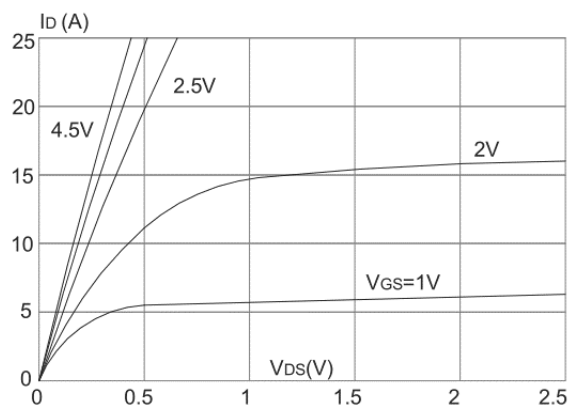
Note 1: Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

**5. Electrical Characteristics at Ta=25°C (Note 2)**

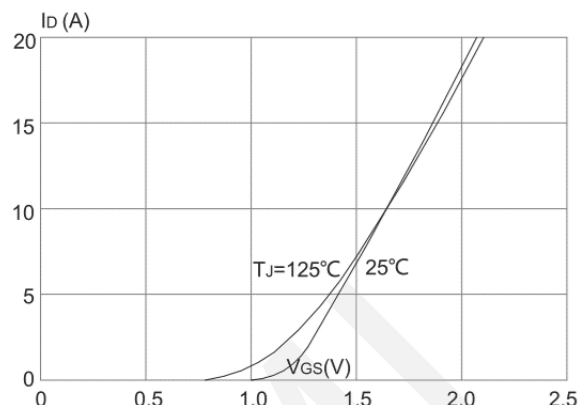
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Units
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$I_D = 250\mu A, V_{GS} = 0V$	20	21	-	V
Zero-Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 20V, V_{GS} = 0V$	-	-	1	$\mu A$
Gate-Body Leakage Current	$I_{GSS}$	$V_{GS} = \pm 12V, V_{DS} = 0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_{DS} = 250\mu A$	0.5	0.8	1.2	V
Drain to Source On-State Resistance	$R_{DS(on)}$	$I_D = 6A, V_{GS} = 4.5V$	-	20	25	m $\Omega$
		$I_D = 4A, V_{GS} = 2.5V$	-	27	35	m $\Omega$
Input Capacitance	$C_{iss}$	$V_{GS} = 0V,$ $V_{DS} = 10V,$ Frequency = 1.0MHz	-	370	-	pF
Output Capacitance	$C_{oss}$		-	89	-	pF
Reverse Transfer Capacitance	$C_{rss}$		-	10	-	pF
Turn-ON Delay Time	$t_{d(on)}$	$V_{DD} = 10V, I_D = 3A,$ $V_{GS} = 4.5V,$ $R_{GEN} = 10\Omega$	-	200	-	ns
Turn-ON Rise Time	$t_r$		-	236	-	ns
Turn-OFF Delay Time	$t_{d(off)}$		-	36	-	ns
Turn-ON Fall Time	$t_f$		-	165	-	ns
Total Gate Charge	$Q_g$	$V_{DS} = 10V,$ $V_{GS} = 4.5V,$ $I_D = 1A$	-	7.5	-	nC
Gate-Source Charge	$Q_{gs}$		-	3.0	-	nC
Gate-Drain Charge	$Q_{gd}$		-	1.5	-	nC
Diode Forward Voltage	$V_{SD}$	$I_S = 5.5A, V_{GS} = 0V$	-	0.9	1.4	V

Note 2: Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

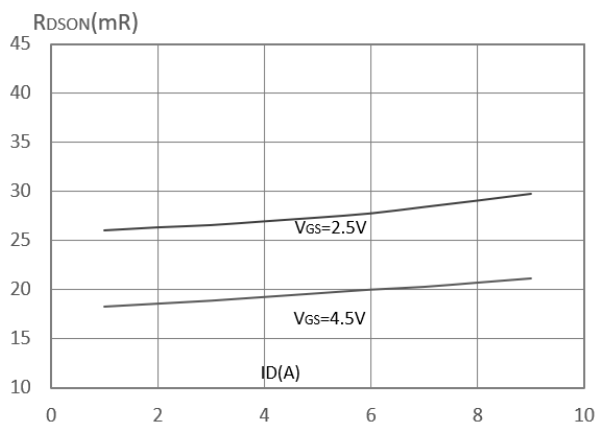
## 6. Typical electrical and thermal characteristics



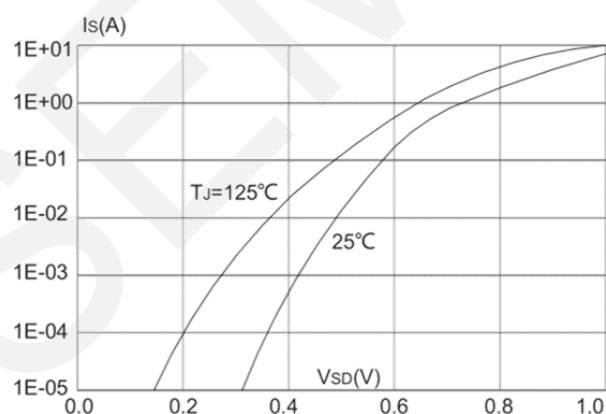
**Output Characteristics**



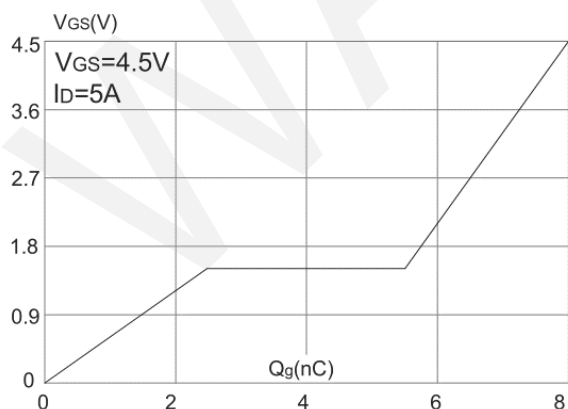
**Typical Transfer Characteristics**



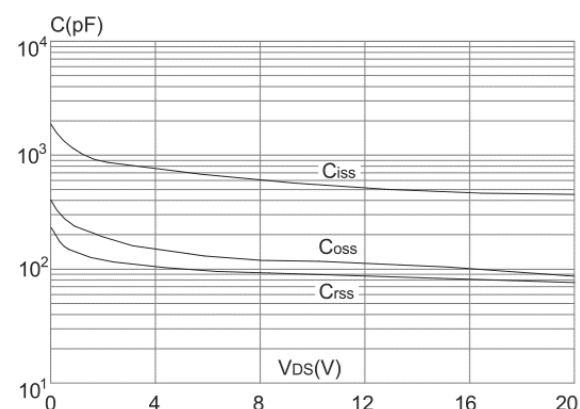
**On-resistance vs. Drain Current**



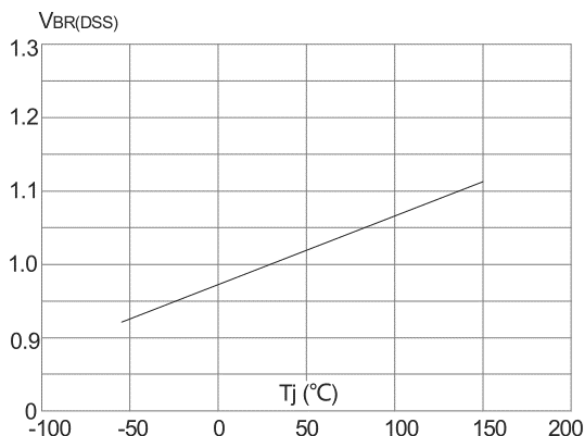
**Body Diode Characteristics**



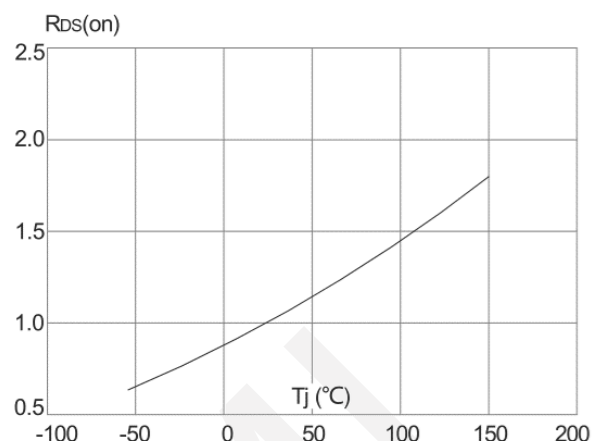
**Gate Charge Characteristics**



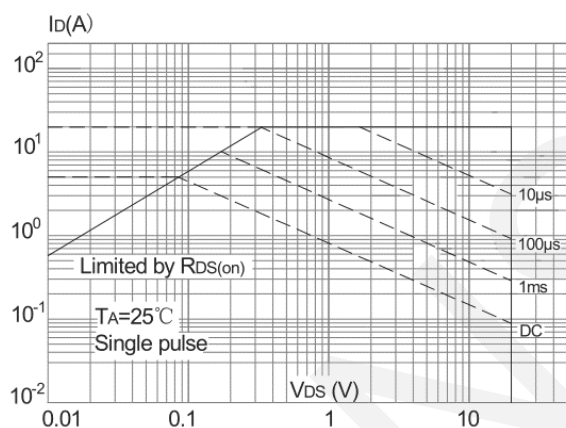
**Capacitance Characteristics**



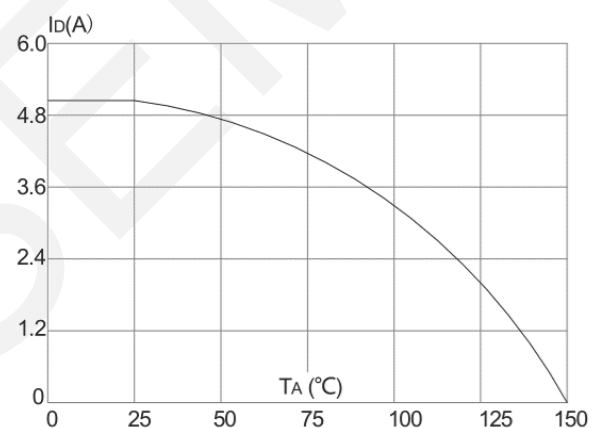
**Normalized Breakdown voltage vs. Junction Temperature**



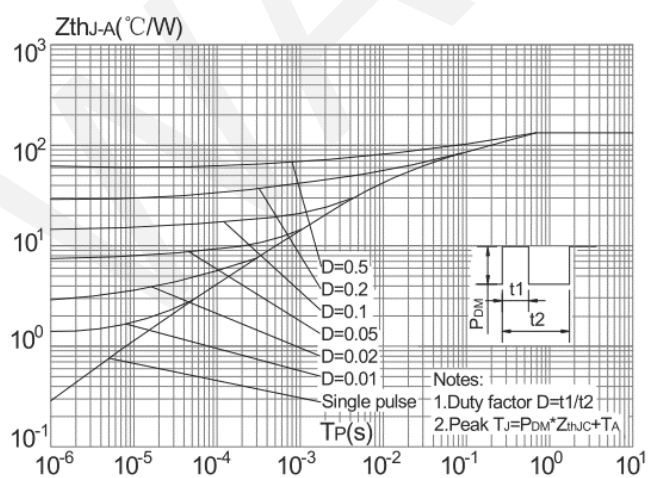
**Normalized on Resistance vs. Junction Temperature**



**Maximum Safe Operating Area**

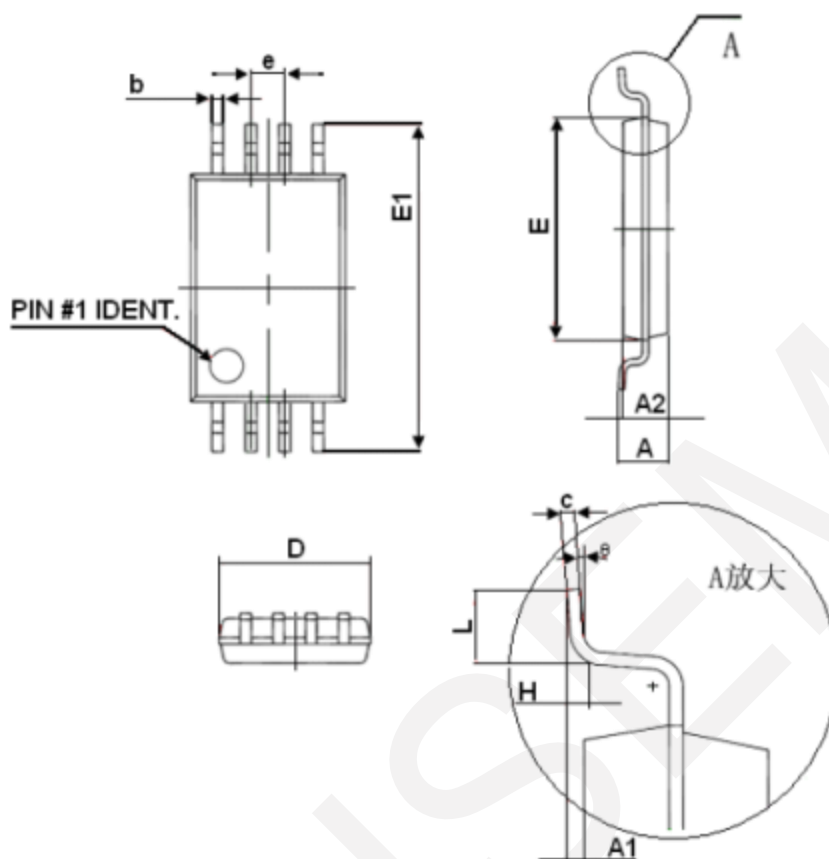


**Maximum Continuous Drain Current vs. Ambient Temperature**



**Normalized Maximum Transient Thermal Impedance**

## 7.Package Dimensions



Symbol	Dimensions In Millimeters	
	Min	Max
D	2.900	3.100
E	4.300	4.500
b	0.190	0.300
c	0.090	0.200
E1	6.250	6.550
A		1.100
A2	0.800	1.000
A1	0.020	0.150
e	0.65(BSC)	
L	0.500	0.700
H	0.25(TYP)	
Θ	1°	7°

## **8.Important Notice**

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